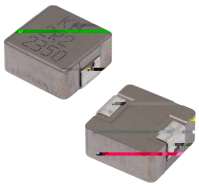
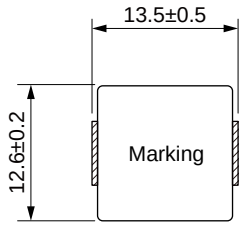
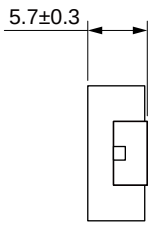
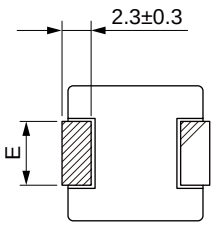
**MDSA Series**
SMD Low Profile High Current Molded Inductor
Size 1360



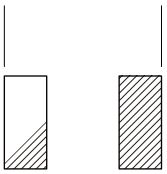
Dimensions: [mm]



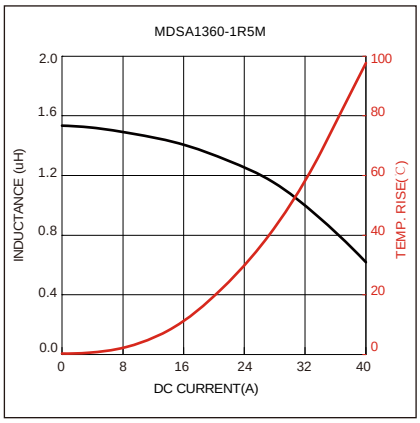

Land Pattern: [mm]

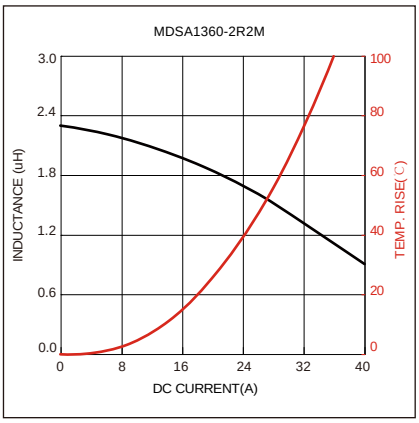


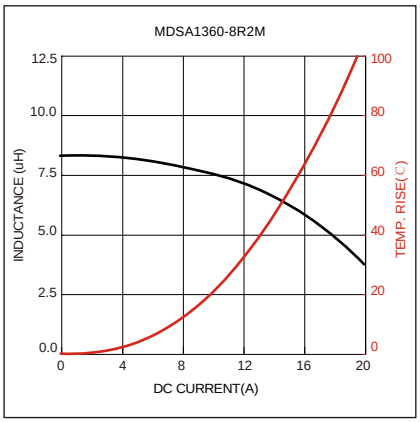
Electrical Properties:

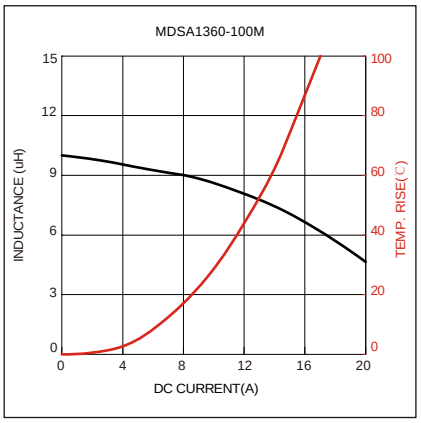
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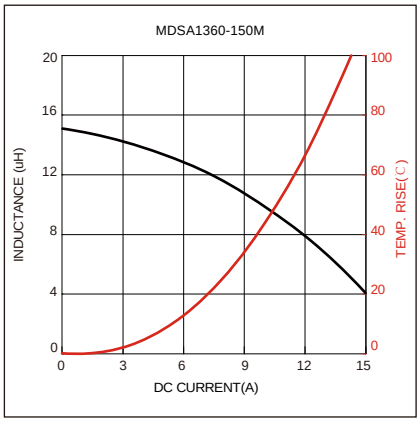
# Typical Electrical Characteristics:

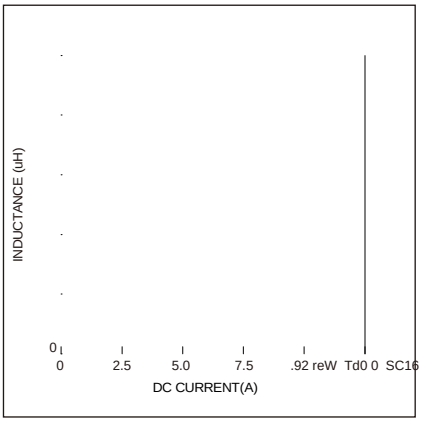


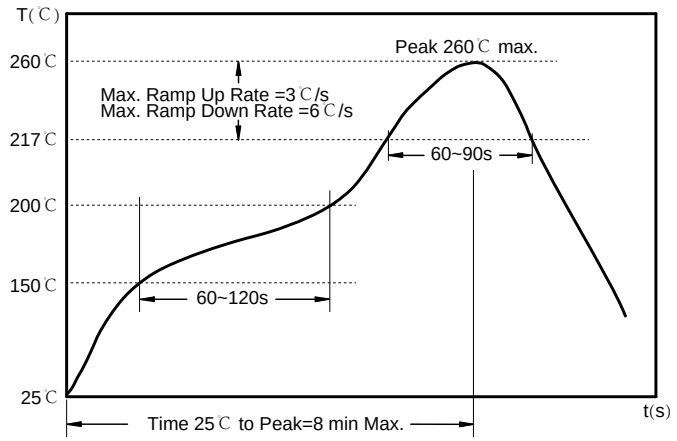



## Soldering Reflow:




Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

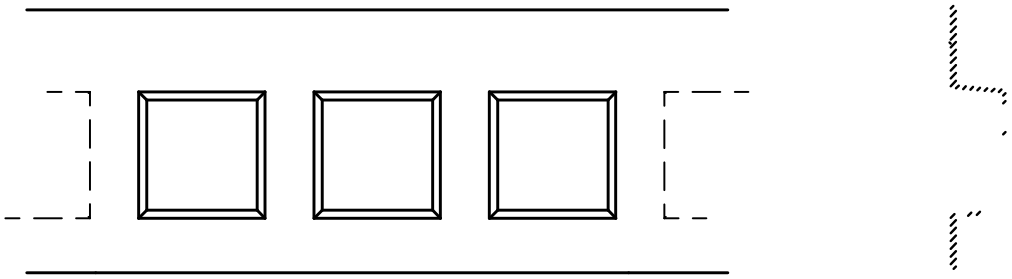
Max temperature: 260℃.

Max time at max temperature: 10 sec.

Allowed Reflow time: 2x max.

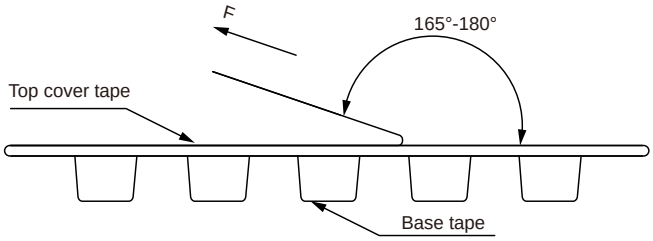
## Packaging Information:

Tape Dimension:



| A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|---|---|---|---|---|---|---|---|---|
| 13.1 ± 0.1 | 14.0 ± 0.1 | 1.5 ± 0.1 | 4.0 ± 0.1 | 16.0 ± 0.1 | 24.0 ± 0.3 | 6.3 ± 0.1 | 1.75 ± 0.1 | 0.50 ± 0.05 |

Peel force of top cover tape:

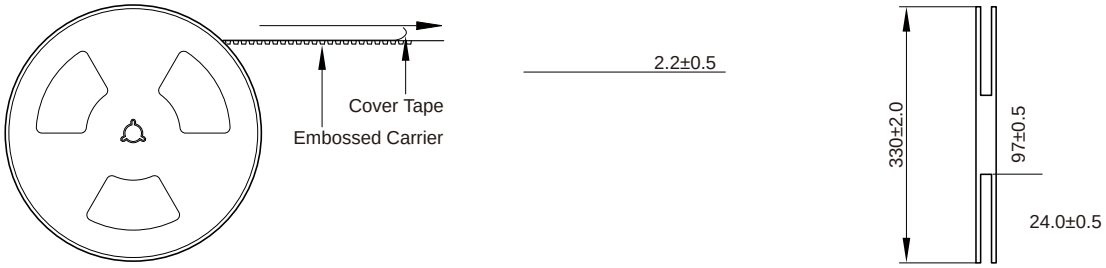



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

| | |
|---|---|
| Marking | KH+Printing Inductance+period) |

Reel Dimension：[mm]




Packaging Quantity: